

Peak Emission Wavelength: 1200nm



Description

- Size 1206: 3.2 (L) x 1.6 (W) x 1.9 (H) mm
- Circuit substrate: glass laminated epoxy
- Devices are RoHS and REACH conform
- Lead free solderable, soldering pads: gold plated
- Marking at anode
- High radiation intensity types

Absolute Maximum Ratings (Ta=25°C)



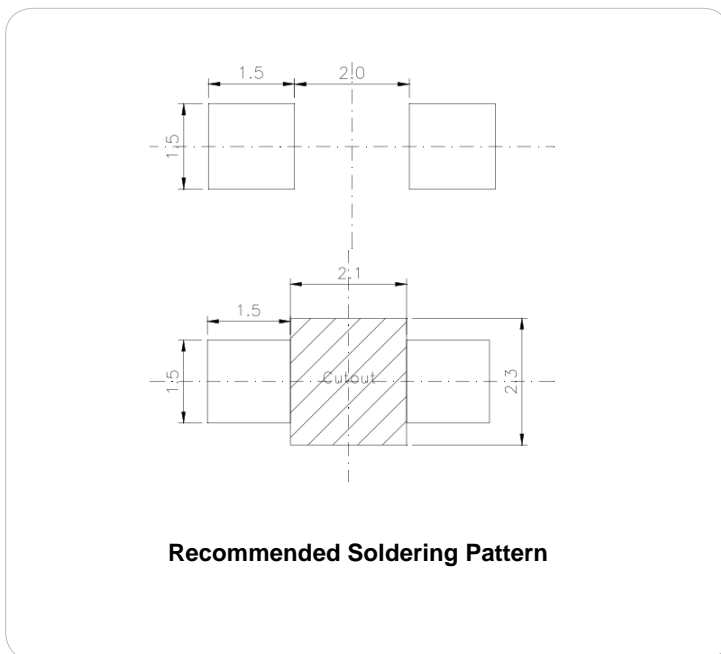
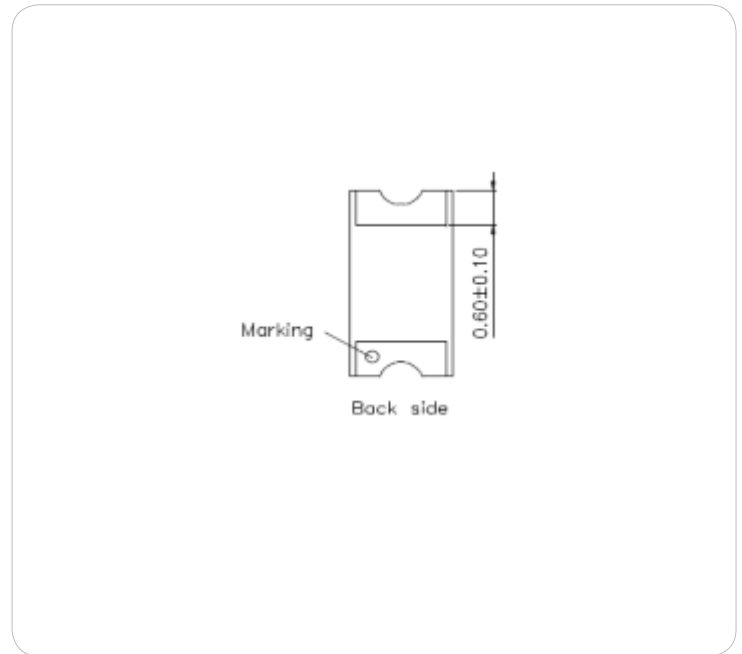
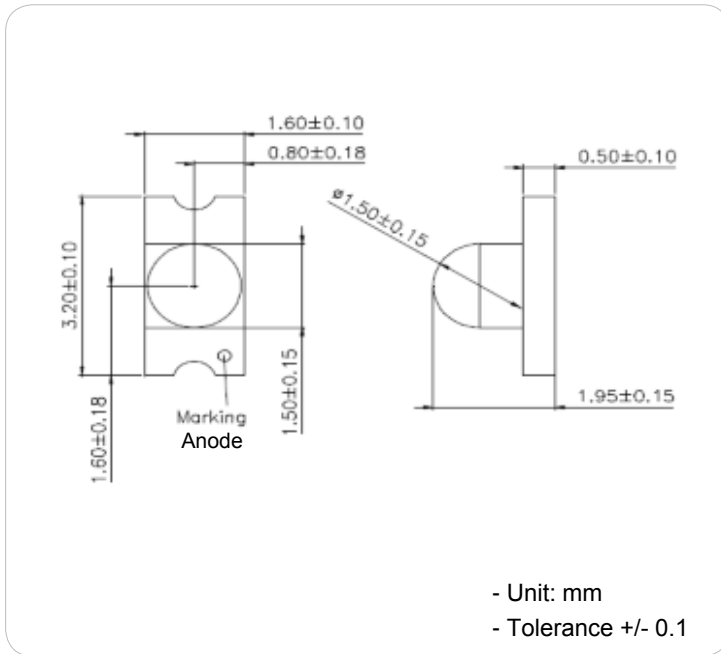
ITEMS	SYMBOL	RATINGS	UNIT
Forward DC Current	If	60	mA
Forward Current, pulsed *	Ifp	200	mA
Reverse Voltage	Vr	5	V
Reverse Current	Ir	100	uA
Operating Temperature	Top	-40 to +85	°C
Storage Temperature	Tst	-40 to +85	°C
Thermal Resistance	RthJA	450	K/W

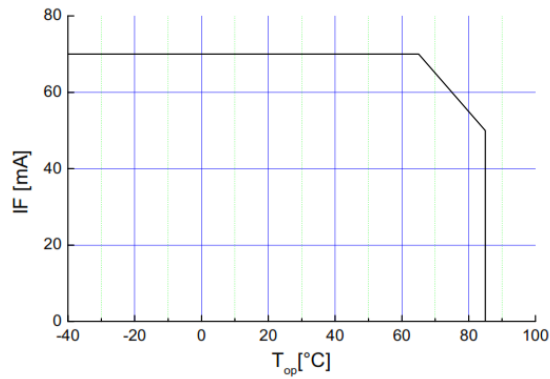
* tp ≤ 100 us, T=1:10

Electrical & Optical Characteristics (Ta = 25°C)

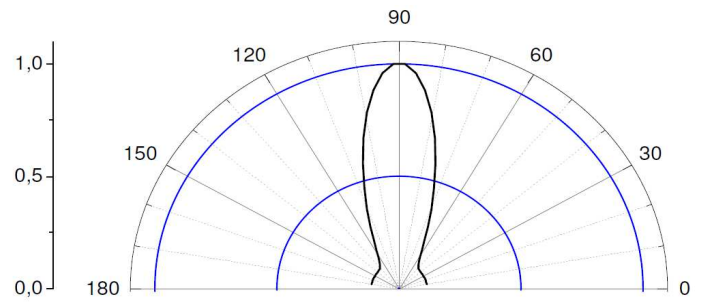
ITEMS	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Forward Voltage	Vf	If=50mA	--	1.3	1.6	V
Peak Wavelength	λp	If=50mA	1150	1200	1250	nm
Radiant Power	Φe	If=50mA	--	12	--	mW
Radiant Intensity	Ie	If=50mA	7.1	15	--	mW/sr
Spectral Bandwidth	Δλ0.5	If=50mA	--	70	--	nm
Viewing Angle	φ	If=50mA	--	40	--	deg

Package Dimensions

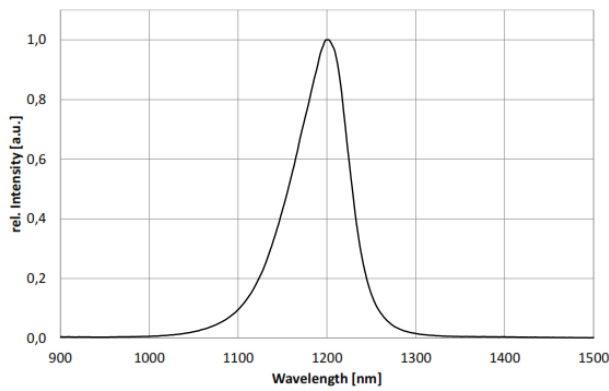




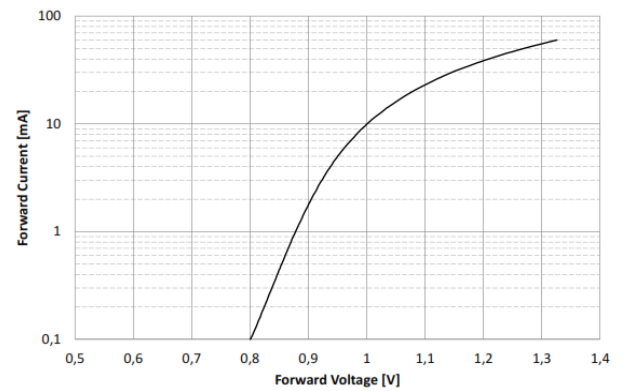
Max. Forward Current vs. Ambient Temperature



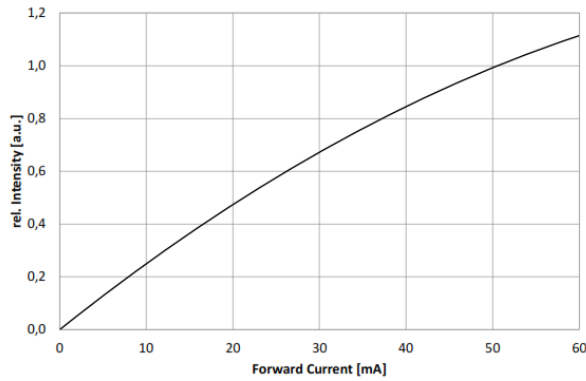
View angle



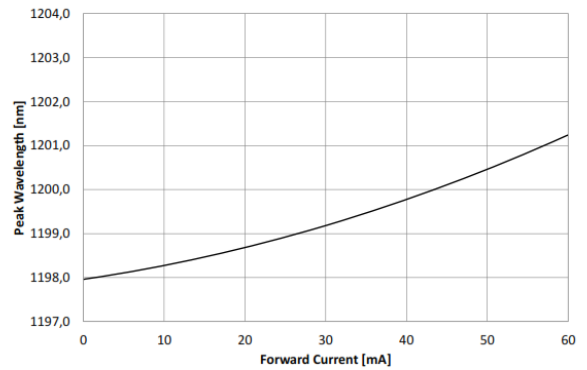
Spectrum



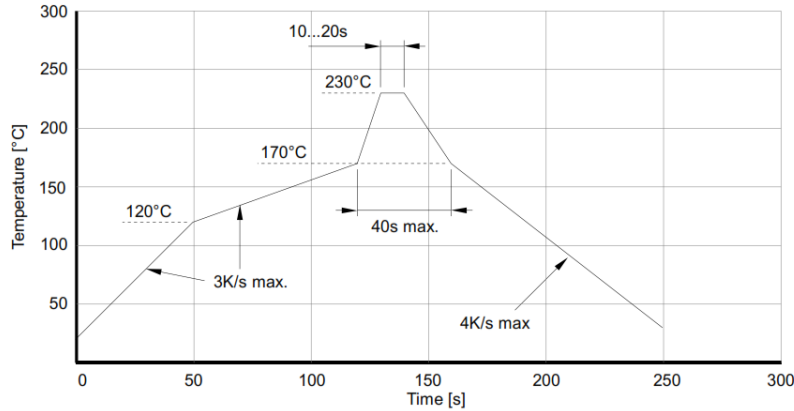
Forward Current vs. Forward Voltage



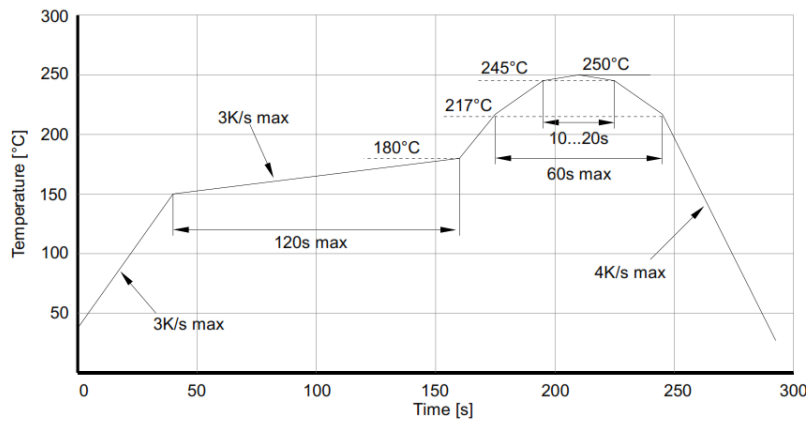
Intensity vs. Forward Current



Forward Current vs. Shift Peak Wavelength



IR reflow soldering profile for lead containing solder



IR reflow soldering profile for lead free soldering

Manual Soldering:

max power of iron 25W / 300°C for 3s